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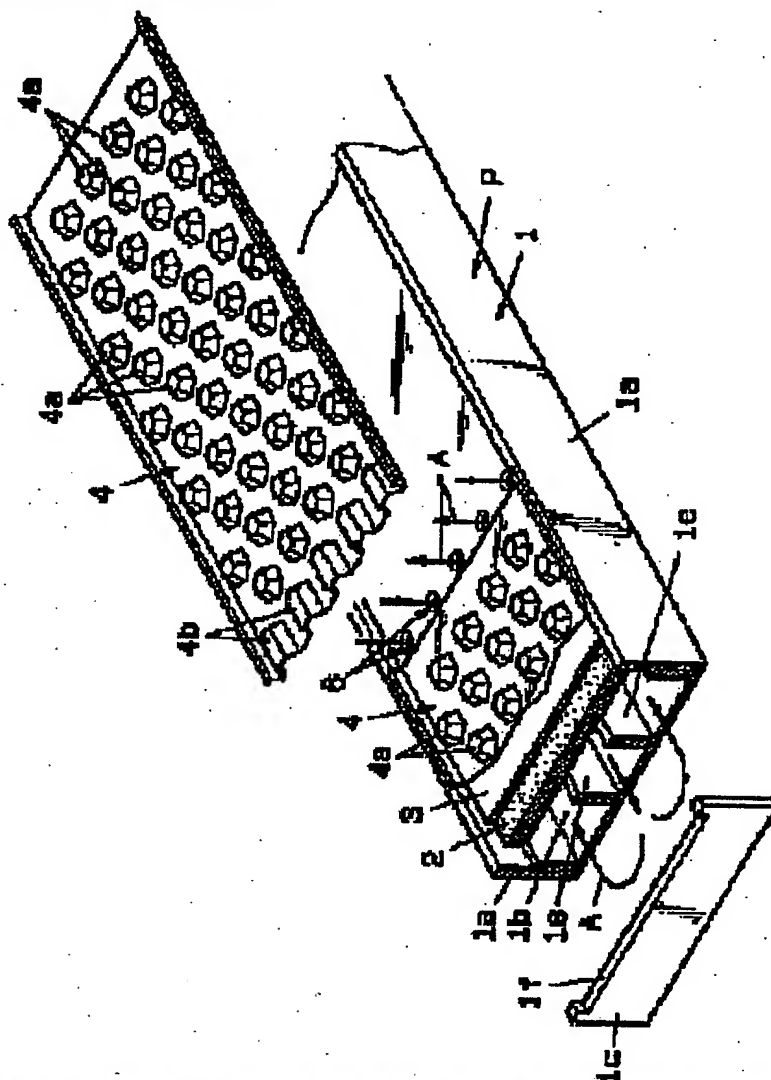
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JP2000160719 (^) A

BUILDING PANEL, ROOF STRUCTURE, AND FLOOR STRUCTURE

YANAGI YUICHI

Inventor(s): YANAGI YUICHI

Application No. 10340541 JP10340541 JP, Filed 19981130, A1 Published 20000613 Published 20000613

Abstract: PROBLEM TO BE SOLVED: To permit melting of roof snow and the use of solar heat (^)

or the like by laying building panels, for enhancing the workability of roof and floor (^) construction work accordingly and for reducing costs.

**SOLUTION:** An upwardly open box-shaped body 1 consisting of right and left side plates, a bottom plate, and front and rear plates is formed and a heat (^) insulating material 2 is arranged between the right and left side plates of the box-shaped body with an air circulation (^) path R1 between the heat (^) insulating material 2 and the bottom plate. A backing plate 3 is arranged on the upper surface of the heat (^) insulating material. A metallic heat (^) exchanging member 4 formed with a plurality of raised placement parts 4a and an air passage R2 between the adjacent raised placement parts is placed on the upper surface of the backing plate and an air inlet communicating the air circulation (^) path to the outside is formed in the box-shaped body. A communication path 6 communicating the air circulation (^) path to an air passage is also formed therein.

**Int'l Class:** E04B00174; E04C00252 E04D01318 E04F01518 F24J00204

**Patents Citing this One:** No US, EP, or WO patents/search reports have cited this patent. **MicroPatent Reference Number:** 000516429

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